MATERIAL DECLARATION DATA SHEET

Device Name	Package Type	Pkg Wt (g)
M2S060	VFG400 (17X17mm)	0.9744

Material Breakdown of Component	Material Breakdown (%)	Substance Name	CAS No.	Weight (g)	Substance Mass (%)
MOLD COMPOUND	36.37	Silica	60676-86-0	0.2977	84.00
		Resin	Proprietary	0.0560	15.80
		Carbon Black	1333-86-4	0.0007	0.20
				0.3544	100.00
SUBSTRATE	44.69	Bismaleimide/Triazine	13676-54-5	0.2859	65.65
		Copper (Cu)	7440-50-8	0.1391	31.95
		Gold (Au)	7440-57-5	0.0017	0.39
		Nickel (Ni)	7440-02-0	0.0088	2.02
				0.4355	100.00
DIE	4.83	Silicon	7440-21-3	0.0471	100.000
				0.0471	100.000
DIE ATTACH EPOXY	0.55	Silver	7440-22-4	0.0041	76.00
		Epoxy resin	Proprietary	0.0013	24.00
				0.0053	100.00
SOLDER BALL	12.10	Tin	7440-31-5	0.1161	98.50
		Silver	7440-22-4	0.0012	1.00
		Copper (Cu)	7440-50-8	0.0006	0.50
				0.1179	100.00
COPPER WIRE	1.45	Copper (Cu)	7440-50-8	0.0139	97.897
		Pd	7440-05-3	0.0003	2.100
		Others	-	0.0000	0.003
				0.0142	100.00
				0.9744	

Disclaimer: Microsemi believes this information to be correct, but cannot guarantee its completeness or accuracy. The information is based on data received from sources outside our company.

Revision No.	Date	Description of Change
1	2015/2/12	Original release
2	2015/11/5	Add M2S060, M2GL060